

### Features

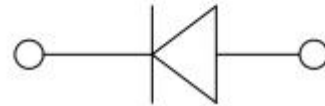
- Low power loss
- Super-fast recovery time for high efficiency
- Glass passivated chip junction
- Low leakage current
- High forward surge capability
- Solder dip maximum peak of 275 °C /7s, per JESD 22-B106

### Typical Application

For use in high frequency rectification and freewheeling application in switching mode converters and inverters for consumer ,computer and telecommunication.

### Mechanical Data

- Package: DO-204AL(DO-41)  
Molding compound meets UL 94 V-0 flammability rating,RoHS-compliant
- Terminals: Tin plated leads, solderable per J-STD-002 and JESD22-B102
- Polarity: Color band denotes cathode end



### Maximum Ratings (Ta=25°C Unless otherwise specified)

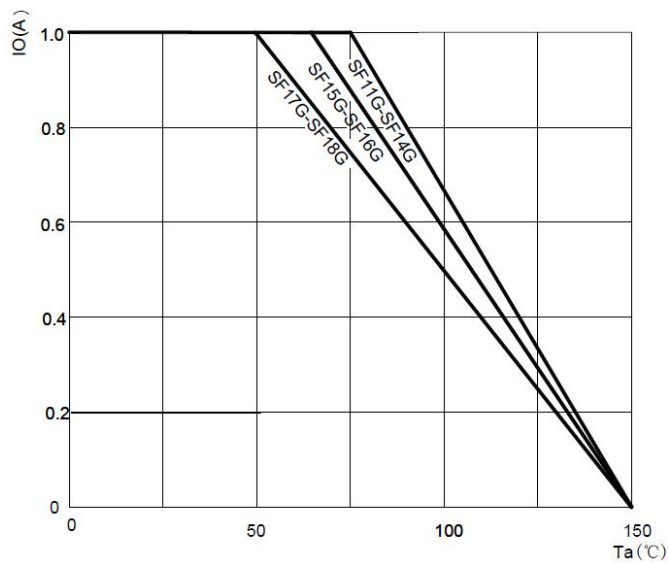
PARAMETER	Symbol	Unit	Conditions	SF1							
				1G	2G	3G	4G	5G	6G	7G	8G
Repetitive Peak Reverse Voltage	$V_{RRM}$	V		50	100	150	200	300	400	500	600
Average Forward Current	$I_{F(AV)}$	A		1.0							
Surge(Nonrepetitive)Forward Current	$I_{FSM}$	A	60HZ sine wave, 1 cycle, Ta=25°C	30							
Storage Temperature	$T_{stg}$	°C		-55 ~ +150							
Junction Temperature	$T_j$	°C		-55 ~ +150							

### Electrical Characteristics (Ta=25°C Unless otherwise specified)

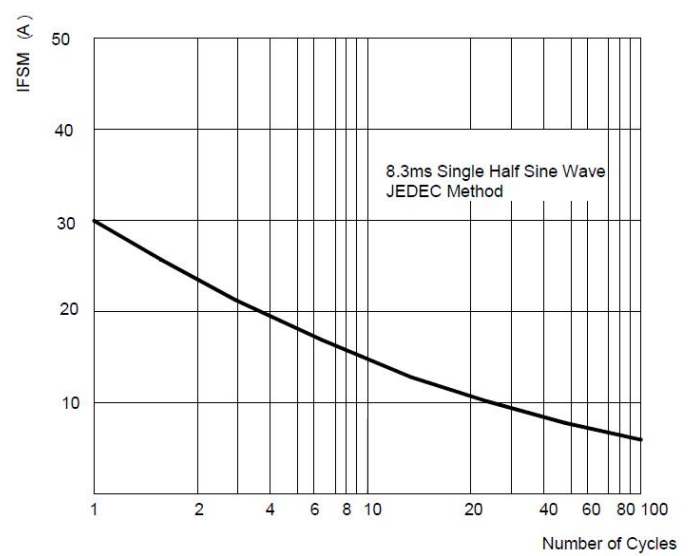
PARAMETER	Symbol	Unit	Conditions	SF1							
				1G	2G	3G	4G	5G	6G	7G	8G
Peak Forward Voltage	$V_{FM}$	V	$I_{FM} = 1.0A$	0.95				1.3		1.7	
Peak Reverse Current	$I_{RRM1}$	$\mu A$	$V_{RM} = V_{RRM}$	$T_a = 25^\circ C$							
	$I_{RRM2}$			$T_a = 125^\circ C$							
Maximum reverse recovery time	$T_{rr}$	ns	$I_F = 0.5A, I_R = 1.0A, I_{rr} = 0.25A$	35							
Thermal Resistance(Typical)	$R_{\theta J-A}$	°C/W	Between junction and ambient	60							
Typical junction capacitance	$C_j$	pF	Measured at 1MHZ and Applied Reverse Voltage of 4.0 V.D.C	40				25			

## Characteristics (Typical)

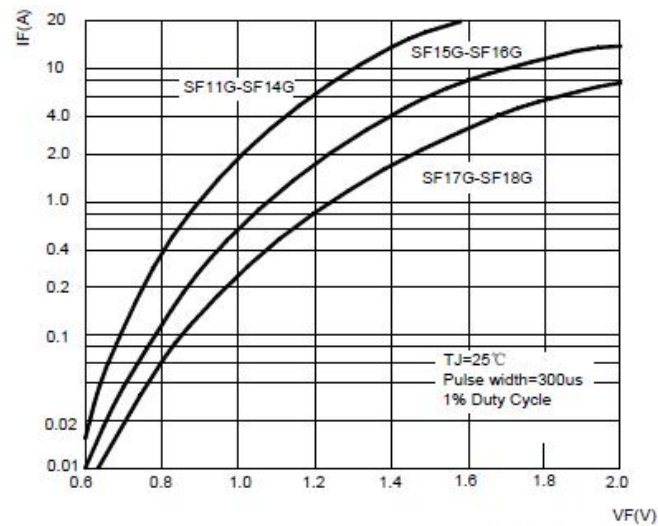
**FIG1: Forward Current Derating Curve**



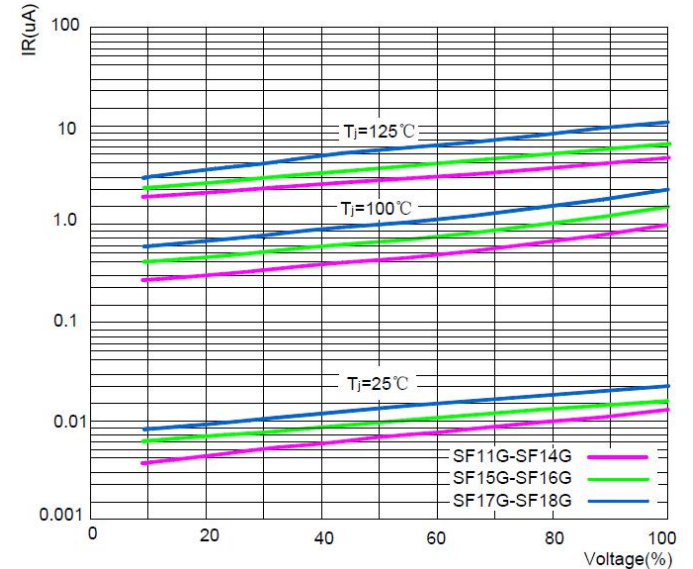
**FIG2: Surge Forward Current Capability**



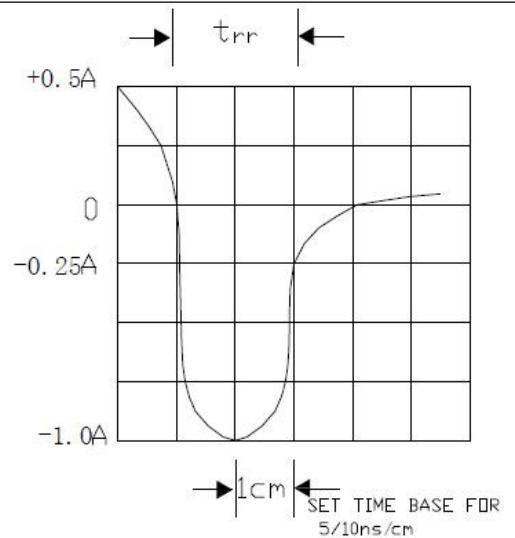
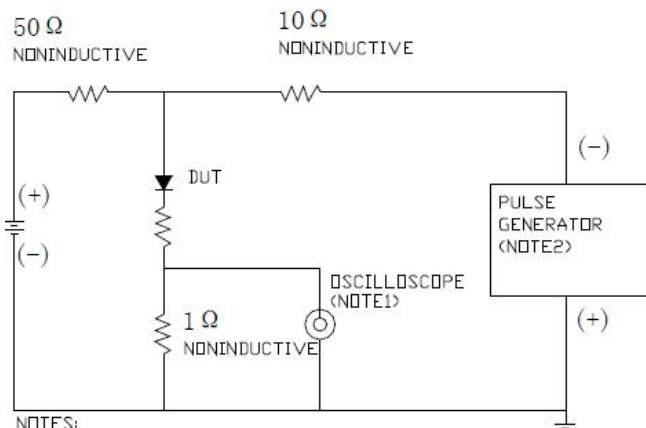
**FIG3: Instantaneous Forward Voltage**



**FIG4: Typical Reverse Characteristics**



**FIG5: Diagram of circuit and Testing wave form of reverse recovery time**



NOTES:  
1. Rise Time=7ns max. Input Impedance=1M Ω 22pF  
2. Rise Time=10ns max. Source Impedance=50 Ω



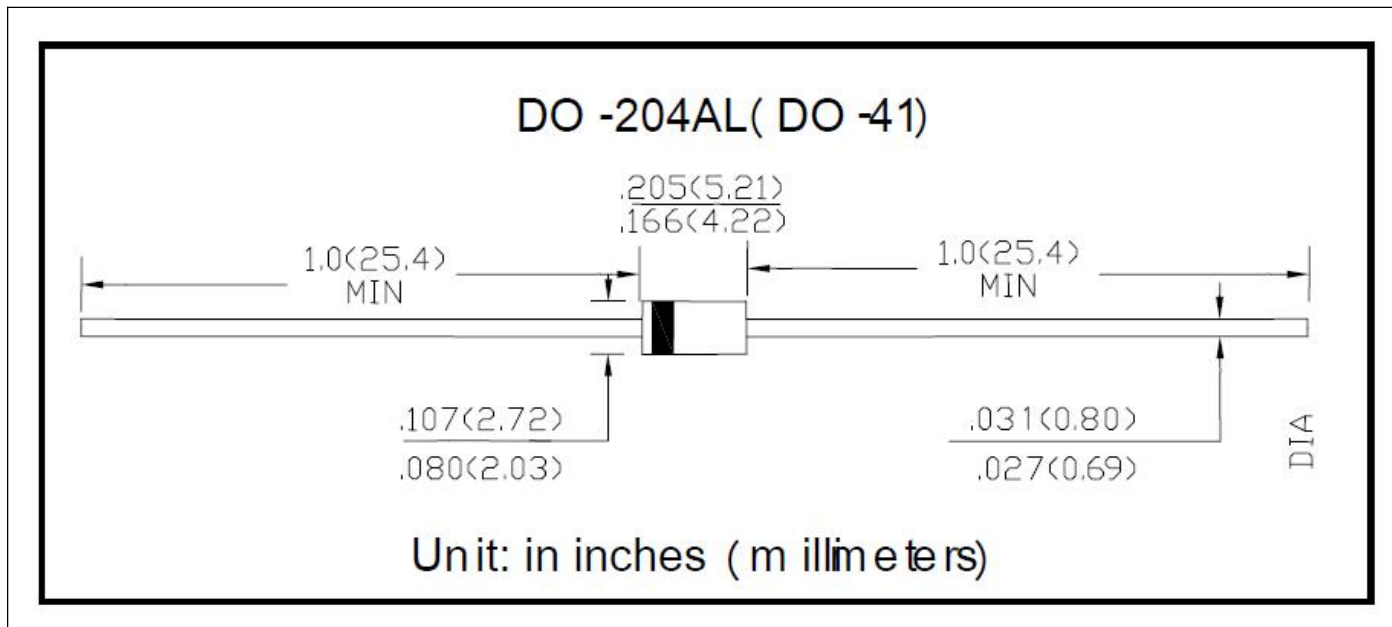
安美半导体  
ANMEI Semiconductor

# SF11G THRU SF18G

## Ordering Information (Example)

PREFERED	PACKAGE CODE	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
SF11G~SF18G	DO-214AL(DO-41)	5000	5000	50000	Tape

## Outline Dimensions



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